

L1SS400T1G

S-L1SS400T1G

Switching Diode

1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Extremely small surface mounting type.
- High Speed.
- High reliability.

2. APPLICATIONS

- High speed switching.

3. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
L1SS400T1G	A	3000/Tape&Reel
L1SS400T5G	A	8000/Tape&Reel

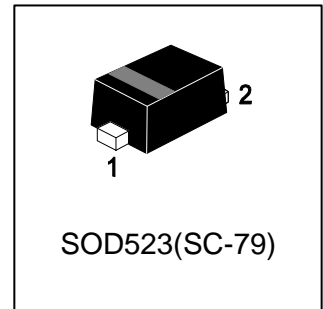
4. MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Limit	Unit
Peak reverse voltage	VRM	100	V
DC reverse voltage	VR	100	V
Peak forward surge current (8.3ms half sine-wave)	IFSM	1.5	A
Mean rectifying current	IO	200	mA
Surge current (1s)	Is	500	mA
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55~+150	°C

5. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-5 Board (Note 1) @ TA = 25°C Derate above 25°C	PD	200 1.6	mW mW/°C
Thermal Resistance, Junction-to-Ambient(Note 1)	RθJA	625	°C/W

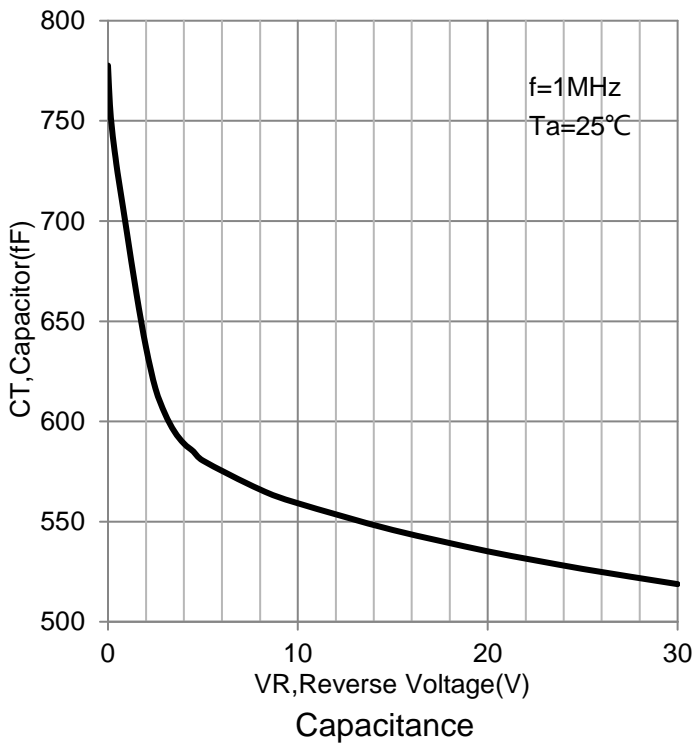
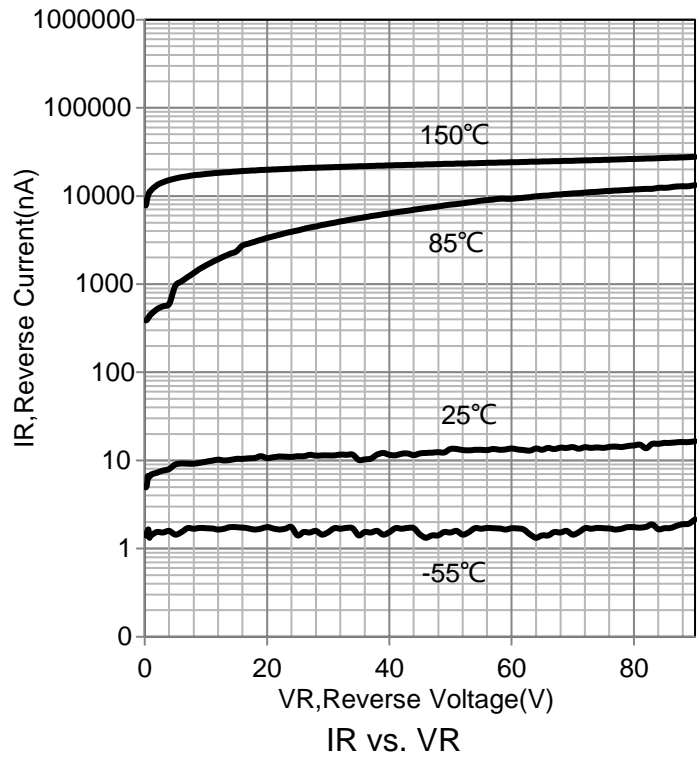
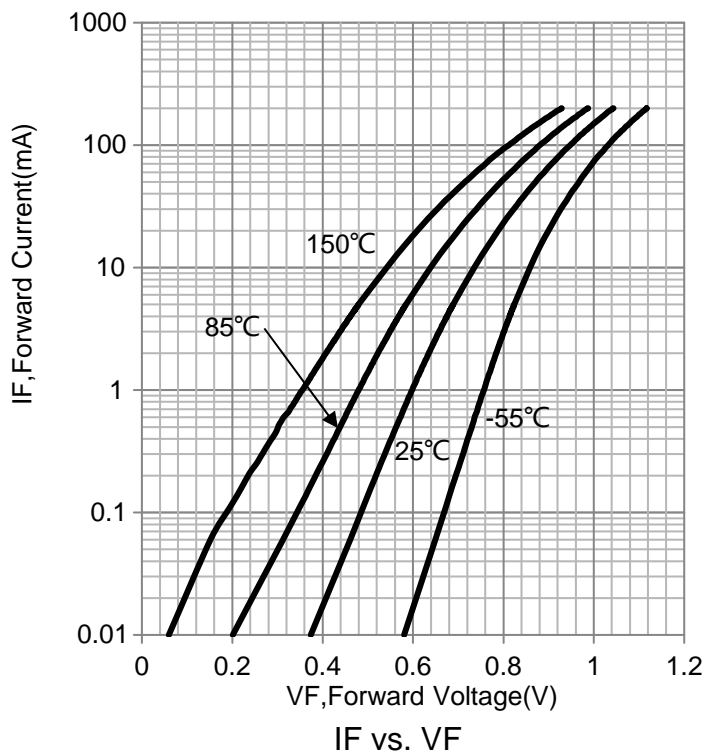
1. FR-5 = 1.0×0.75×0.062 in.



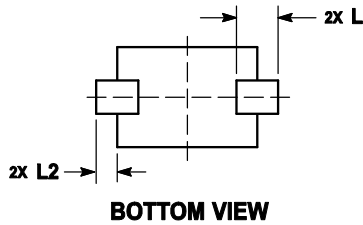
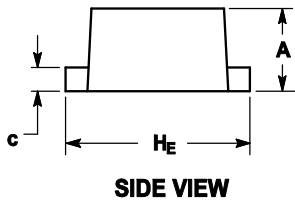
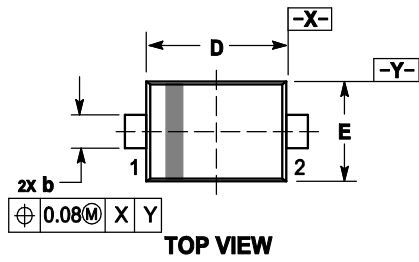
6. ELECTRICAL CHARACTERISTICS (T_j =25°C unless otherwise specified.)

Parameter	Symbol	Min	Typ.	Max	Unit
Forward voltage (I _F =100mA) (I _F =200mA)	V _F	- -	- -	1.2 1.25	V
Reverse current (V _R =80V) (V _R =100V)	I _R	- -	- -	0.1 0.5	μA
Capacitance between terminals (V _R =0.5V , f=1MHz)	C _T	-	0.72	3	pF
Reverse recovery time (V _R =6V,I _F =10mA , R _L =100Ohm)	t _{rr}	-	-	4	ns

7.ELECTRICAL CHARACTERISTICS CURVES



8. OUTLINE AND DIMENSIONS



Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.07	0.14	0.20	0.003	0.006	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
E	0.70	0.80	0.90	0.028	0.031	0.035
H _E	1.50	1.60	1.70	0.059	0.063	0.067
L	0.30 REF			0.012 REF		
L ₂	0.15	0.20	0.25	0.006	0.008	0.010

9. SOLDERING FOOTPRINT

